



EC Declaration of Conformity

Issuer's Name: **Artesyn Embedded Technologies**
Issuer's Address: 3rd /4th Flr. Techno Plaza One Bldg.
18 Orchard Rd., Eastwood City Cyberpark,
Libis, Quezon City, Philippines

Product Description: **MPC7457 1GHZ, 512MB SDRAM, IEEE HANDLE, 6E, respin**

Type Designation: **MVME55006E-0163R**

We hereby certify the designated product is in conformity with European Directive, REACH, EC Regulation No. 1907/2006.

For details of REACH 181 SVHC's, please see the European Chemical Agency (ECHA) web site:

<http://echa.europa.eu/web/guest/candidate-list-table>

Pursuant to the European Court of Justice ruling published Sept 15, 2015, we are notifying the customer of the presence of SVHC's in excess of 0.1% w/w of the component article.

Name of SVHC substance	Cas No	Content Concentration (%)	Location/s (which component contain)
2,2',6,6'-Tetrabromobisphenol A	79-94-7	0.60	IC
Antimony trioxide	1309-64-4	1.07	Capacitor
Antimony trioxide	1309-64-4	2.16	Diode
Antimony trioxide	1309-64-4	1.47	IC
Antimony trioxide	1309-64-4	0.32	Semicon
Antimony trioxide	1309-64-4	0.90	Battery
Antimony, elemental	7440-36-0	1.55	IC
Bismuth	7440-69-9	0.75	IC
Bismuth oxide	1304-76-3	0.86	Resistor
Bismuth oxide	1304-76-3	0.86	Ferrite Beads
Brominated bisphenol diglycidyl ether	40039-93-8	1.07	Capacitor

Diboron trioxide	1303-86-2	0.35	Capacitor
Diboron trioxide	1303-86-2	0.59	Resistor
Hexahydromethylphthalic anhydride	25550-51-0	0.53	Connector
Hexahydromethylphthalic anhydride	25550-51-0	0.12	IC
Lead	7439-92-1	3.15	Diode
Lead	7439-92-1	2.10	Rectifier
Lead	7439-92-1	0.76	Regulator
Lead	7439-92-1	17.77	Fuse
Lead	7439-92-1	1.29	IC
Lead	7439-92-1	4.56	Mosfet
Lead monoxide	1317-36-8	2.15	Resistor
Lead silicate	65997-18-4	1.66	Resistor
Lead silicate	65997-18-4	0.74	Capacitor
N,N-dimethylacetamide	127-19-5	1.00	Label

REACH SVHC reporting in compliance with 1907/2006EC has been verified via internal design controls, supplier declarations and/or analytical test data.


Rose Gerardo
 Materials Compliance Engineer
Artesyn Embedded Technologies
Date: 22/ March / 2018